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INNOS
創新服務股份有限公司

Innostar Service Inc.

Nov 2025

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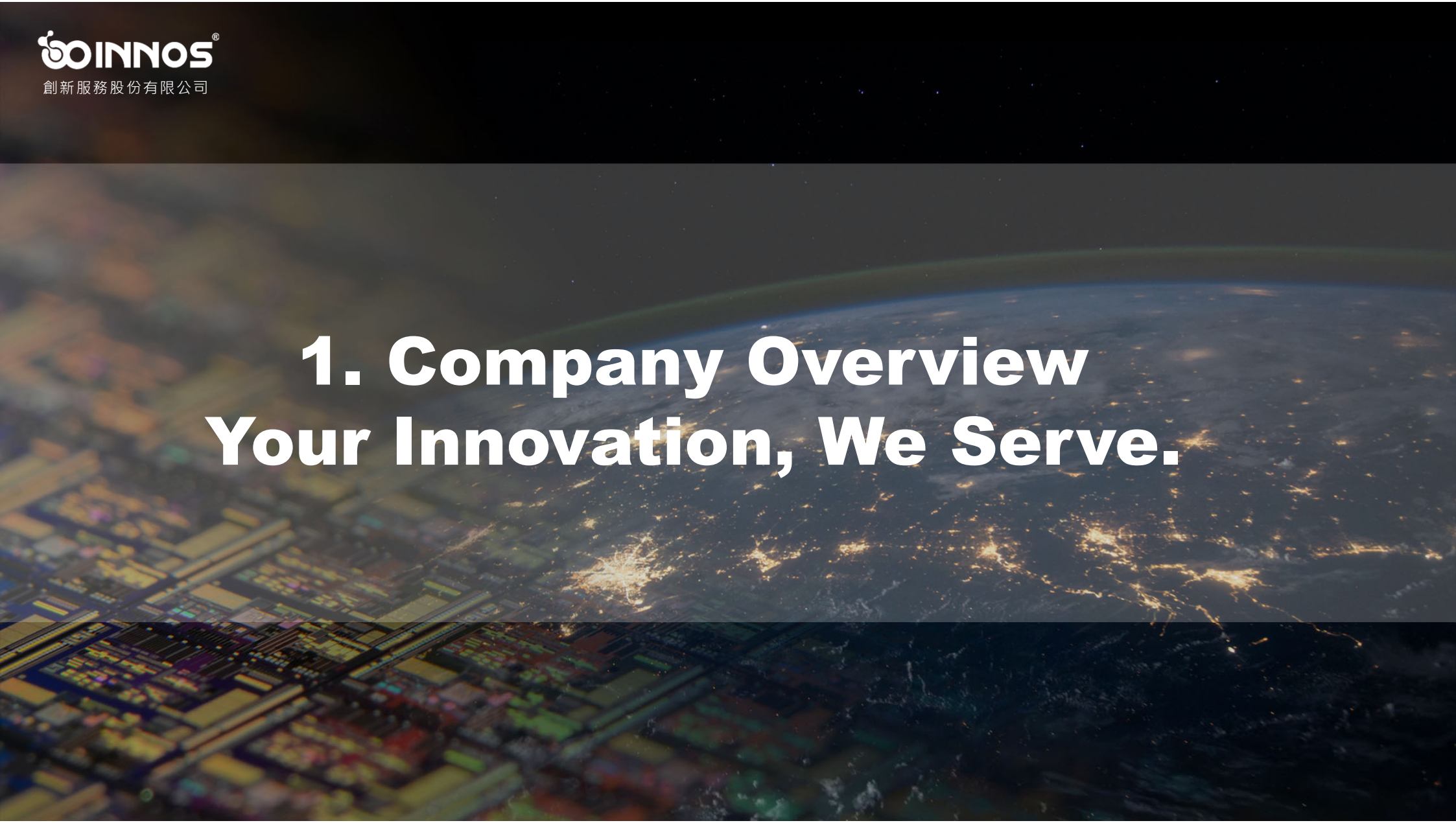
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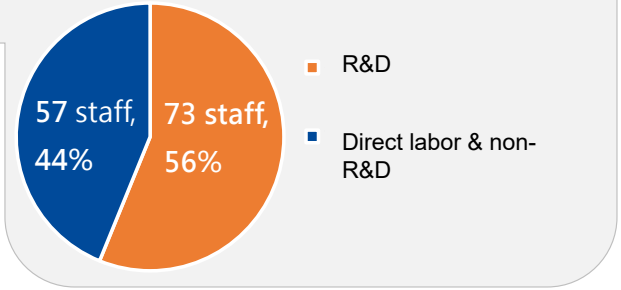
1. Company Overview
Your Innovation, We Serve.

Company Overview

創新服務股份有限公司
InnoStar Service, Inc.

- Established: 2004
- Capital: NTD 367 million
- Employees: 130
- Locations
  - Hsinchu Plant
  - Taichung Headquarters
  - Kaohsiung Office
- Core Businesses
  - Development, manufacturing, and sales of semiconductor automation equipment
  - Advanced packaging solutions
  - Development, manufacturing, and sales of advanced packaging components
  - Probe card maintenance and repair, services and sales of related materials

R&D talent accounts for **56%** of total headcount





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Key Milestones

2004

- Company established
- Launched first-gen automatic plastic lens-cutting machine
- **Pioneered automation revolution for optical industry**

2014

- Expanded into advanced semiconductor testing, developed MEMS Probe Card Assembly Equipment for wafer testing
- **Pioneered automation revolution for probe card industry**

2016

OEM service of MEMS needle assembly for leading foundries, having processed more than 300 million units

2022

Auto Needle Assembly Machine adopted by leading probe card makers

2024

High-density Cu Pillar Lead Frame applied to WIFI modules with substantial sample shipments

Needle Assembly Machine adopted at scale by probe card makers



2025

High-density Cu Pillar Lead Frame applied to power modules, TGV, and PLP modules

- Technoprobe became strategic investor
- Launched comprehensive MEMS probe card automation solutions



2026

To verify and mass-produce High-density Cu Pillar Lead Frame modules

- **To expand the MEMS probe card equipment lineup**
- **To establish and realize probe card repair capacity**

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Product Portfolio

Complete Probe Card Equipment Automation Solutions

- Laser Drilling Machine
- Guide Plate Inspection and Lamination Machine
- Dual-arm Needle Assembly Machine
- Probe Card Inspection Machine
- Laser Reshaping Machine, Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Binning and Aligning Machine
- CoWoS FT Auto Probe Assembly (90um) and Inspection Machine



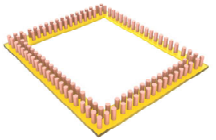
MEMS Probe Card Repair Lineup

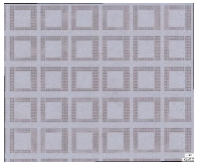
High-Precision Semiconductor Processing

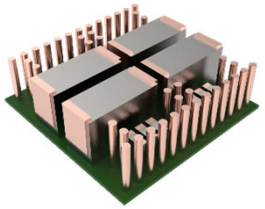
- High-Precision Laser Cutting Machine
- Mini LED Laser Repair Equipment
- Laser De-coating Machinery
- MEMS Mirrors Precision Assembly Machine
- CoWoS Substrate Component Repair Equipment
- High-Precision Spot Welding Machine

Advanced Packaging

- WIFI Module High-Density Cu Pillar Lead Frame
- Power Module High-Density Cu Pillar Lead Frame
- Interposer (10:1) Cu Pillar TGV







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End-to-End Automation Solutions for MEMS Probe Cards

INNOS End-to-End Probe Card Manufacturing and Repair Equipment

Laser Drilling Machine (LS-11)	Guide Plate Inspection and Lamination Machine (PHIA-02)	Dual-arm Needle Assembly Machine (AT-105)	Probe Card Inspection Machine (PCR-01)	Laser Reshaping Machine (PHR02) & Laser Cleaning Machine (PHC-02)	Auto Probe Change Machine (PIR-02)	Probe Binning and Aligning Machine (PSA-01)
Development completed	Completion expected 1Q26	Development completed	Development completed	Development completed	Development completed	Development completed



Conventional Probe Card Manufacturing Processes

Laser drilling machine	Manual & semi-auto lamination	Manual needle assembly	Manual microscopic inspection	Semi-auto laser cleaning	Manual probe replacement & measurement	Manual binning

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2. New High-Value Products & Growth Drivers

Timeline of MEMS Probe Card Automation/Repair Equipment and Material Kit Sales

#	MEMS probe card-related product	2016-2021	2022 2023	2024	2025				2026			
					Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
1	**Single-arm Needle Assembly Machine**	Needle assembly OEM	Sales start	**Scaled sales**								
2	**Dual-arm Needle Assembly Machine**				Under Development	Under Development	Under Development	**Mass production & shipments**				
3	**Probe Card Inspection Machine**					Under Development	Under Development	**Mass production & shipments**				
4	**Laser Reshaping Machine & Laser Cleaning Machine**					Under Development	Under Development	**Mass production & shipments**				
5	**Auto Probe Change Machine**					Under Development	Under Development	**Mass production & shipments**				
6	**Probe Binning and Aligning Machine**						Under Development	Under Development	**Mass production & shipments**			
7	**5-axis Laser Drilling Machine**				Under Development	Under Development	Under Development	Under Development	**Mass production & shipments**			
8	**Guide Plate Inspection and Lamination Machine**					Under Development	Under Development	Under Development	**Mass production & shipments**			
9	**Probe Card Analyzer**							Under Development	Under Development	**Mass production & shipments**		
10	**Probe card repair OEM service**								Production line build	Production line build	**Contract manufacturing**	**Contract manufacturing**
11	**Probe card material kits**					Contract signing/market promotion	Applied to customers' designs	**Limited shipments**	**Sales start**	**Sales start**	**Sales start**	**Sales start**

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High-Density Cu Pillar Lead Frame: Product Launch Progress

Target Sector	Number of Customers	Number of Projects	Progress
TGV High-speed Transmission Module	3	3	• NTI → NPI → **Mass production after 2026**
AI Power Module	8	12	• NTI → EVT/DVT → PVT → **Mass production and product launch expected 2027**
RF/Network Communications	5	11	• EVT/DVT → PVT → **Mass production starting in 2026**
VR/AR	2	2	• Now in NTI / NPI, with mass production in planning

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New Facility in Taichung: First-Phase Construction

- First-phase construction to be completed in 1Q26
- Cu Pillar Module line
  - Expand to **4** production lines (expected)
  - Production capacity: **10,000K** pcs/year
- TGV-ICP production line
  - Expand to **12** production lines (expected)
  - Production capacity: **120K** pcs/year



Land acquired on Aug 6, 2025
Land: No. 686, 687, 687-1, Guangming Rd., Dajia Dist., Taichung City
Building: No. 130-1 Xing'an Rd., Dajia Dist., Taichung City
Land area: 3,558.00 km^2
Building area: 3,945.35 km^2
First-phase construction to be completed in 1Q26; second-phase construction to start in 1Q27

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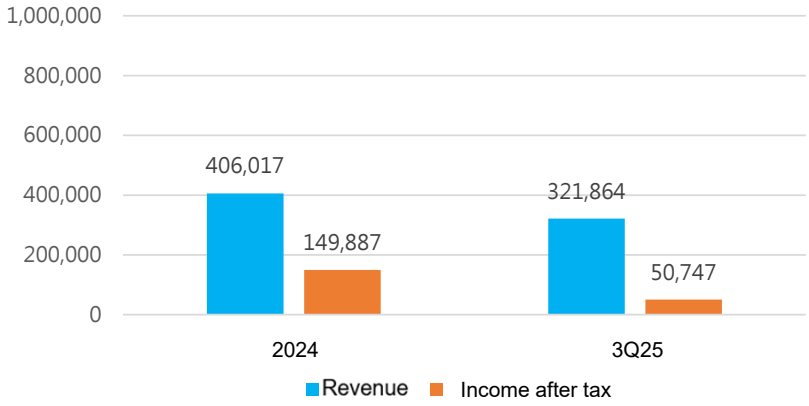


3. Performance & Outlook

Business Performance

2024-3Q25 Financial Performance

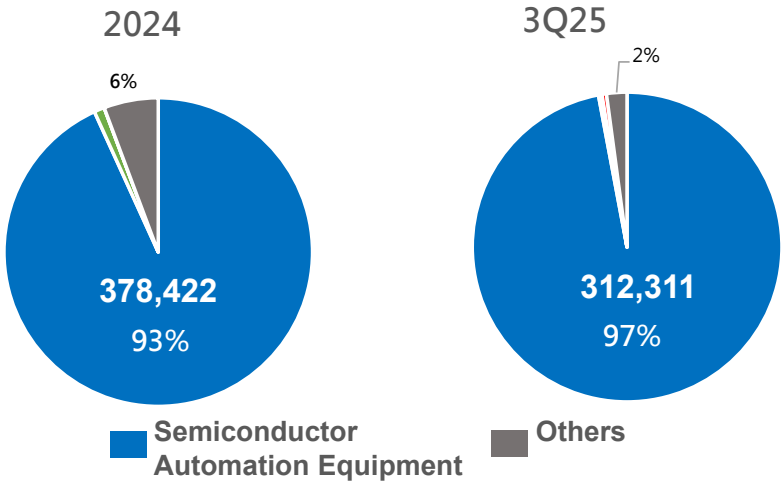
Unit: NTD 1,000



	2024	3Q25
Revenue	406,017	**321,864**
Income after tax	149,887	**50,747**
Gross margin	80%	**73%**
EPS	5.25	1.42

Revenue Mix by Major Products

Unit: NTD 1,000

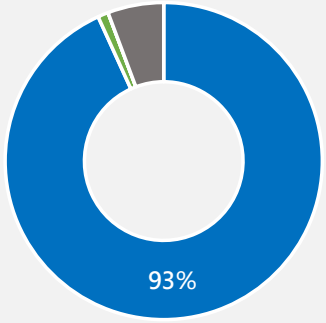


- **Business Performance:** As of 3Q25, cumulative revenue reached NTD 321,864,000, EPS was NTD 1.42, and gross margin was 73%, reflecting solid profitability. Strong revenue growth was driven by **rising AI demand** and stable shipments of MEMS probe card–related equipment.
- **Outlook for This Year :** Shipments of MEMS probe card–related equipment are expected to **remain steady**. The strategically planned **probe card material kits** began low-volume shipments in 4Q25, and various projects for the **Cu pillar mass-transfer module** are currently undergoing sample verification.

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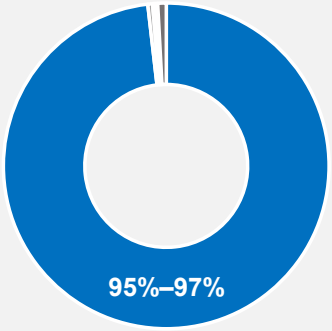
Revenue Structure Shift: Four-Year Comparison

2024



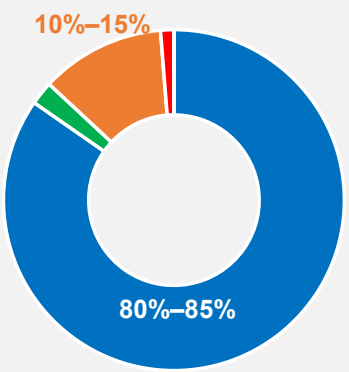
- Semiconductor equipment accounting for 93% of total revenue. Breakdown by type:
  - Single-arm Needle Assembly Machine: > 20 units
  - Laser Repair Equipment: 1 unit
- Others (incl. revenue from Cu pillar mass-transfer modules): 7%

2025



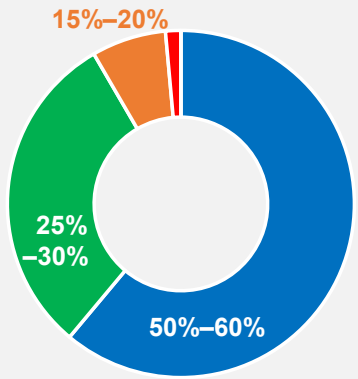
- Semiconductor equipment accounting for 95%–97% of total revenue. Breakdown by type:
  - Dual–arm Needle Assembly Machine
  - 5-axis Laser Drilling Machine
  - Laser Reshaping Machine & Laser Cleaning Machine
  - Auto Probe Change Machine
  - Probe Card Inspection Machine
  - Probe Binning and Alignment Machine
  - Auto Pogo Pin Assembly Machine
  - MEMS Mirrors Precision Assembly Machine
- Others (Revenues from Cu pillar mass-transfer modules + probe card material kits +probe card repair service): 3%–5%

2026



- Semiconductor equipment accounting for 80%–85% of total revenue. Breakdown by type:
  - Dual–arm Needle Assembly Machine
  - 5-axis Laser Drilling Machine
  - Laser Reshaping Machine & Laser Cleaning Machine
  - Auto Probe Change Machine
  - Probe Card Inspection Machine
  - Probe Binning and Alignment Machine
  - Auto Pogo Pin Assembly Machine
  - MEMS Mirrors Precision Assembly Machine
- Revenues from probe card material kits + repair +repair service:10–15%
- Others (incl. revenue from Cu pillar mass-transfer modules): 5%–10%

2027



- Semiconductor equipment accounting for 50%–60% of total revenue. Breakdown by type:
  - Dual–arm Needle Assembly Machine
  - Laser Drilling Machine
  - Laser Reshaping Machine & Laser Cleaning Machine
  - Auto Probe Change Machine
  - Probe Card Inspection Machine
  - Probe Binning and Alignment Machine
  - Auto Pogo Pin Assembly Machine
- Revenue from Cu pillar mass-transfer modules: 25%–30%
- Others (inc. revenues from probe card material kits + repair service) : 15%–20%

Semiconductor automation equipment revenue | Cu pillar mass-transfer module revenue | Probe card material kit revenue | Probe card repair service revenue | Others

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Three Core Pillars Established: 2026-2027 Major Business Segments Explained

2026 –speeding transformation

- Dual-arm Needle Assembly Machine
- Laser Drilling Machine
- Laser Reshaping Machine & Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Card Inspection Machine
- Probe Binning and Alignment Machine
- Auto Pogo Pin Assembly Machine
- MEMS Mirrors Precision Assembly

- Equipment: **80%–85%**
- Probe card material kits + probe card repair service: **10%–15%**
- Cu pillar mass-transfer modules: **5%–10%**

Notes: The revenue contribution from equipment has begun to decline. Market promotion and customer validation for the probe card material kits require a longer cycle, but early results will emerge in 2026, contributing 15% of revenue.

2027 –Three core pillars established

- Dual-arm Needle Assembly Machine
- Laser Drilling Machine
- Laser Reshaping Machine & Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Card Inspection Machine
- Probe Binning and Alignment Machine
- Auto Pogo Pin Assembly Machine

- Equipment: **50%–60%**
- Cu pillar mass-transfer modules: **25%–30%** •TGV-ICP
- Probe card material kits + probe card repair service: **15%–20%**

Notes: Following several years of sample delivery to customers and validation, certain Cu pillar mass-transfer modules are expected to enter mass production, establishing a dual-pillar revenue model of “equipment + high-value products.” Among the three core pillars, the probe card material kit represents a new market that requires a longer development cycle and remains the Company’s mid- to long-term goal.

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4. Q & A

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